# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

| HP ProDesk 400 G2.5 SFF Business PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>Cooler fan 82g, system fan 72g, PSU fan 32.4g</td>
<td>186.4g</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>YN-3</td>
</tr>
<tr>
<td>Screw driver</td>
<td>PH2</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel. (see Figure 1-2)
2. Remove front bezel. (see Figure 3)
3. Disconnect cooler cable then remove the cooler from board. (see Figure 4-5)
4. Remove the HDD (see Figure 6-8)
5. Remove the Slim ODD (see Figure 9-10)
6. Unplug all cable conn. from PCA. (see Figure 11)
7. Remove the PCA (see Figure 12-13)
8. Remove the DIMM. (see Figure 14)
9. Remove the CPU. (see Figure 15-16)
10. Remove the Battery. (see Figure 17)
11. Remove the FIO module from chassis. (see Figure 18-19)
12. Remove the SD card reader from chassis. (see Figure 20-21)
13. Remove the speaker from chassis. (see Figure 22-23)
14. Remove Sys fan from chassis. (see Figure 24-25)
15. Remove the PSU from chassis. (see Figure 26-27)
16. Remove the PSU chassis and remove the PSU board. (see Figure 28-38)
17. Remove the Electrolytic Capacitors from PSU board. (see Figure 39-40)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Release Thumb screw on the access panel.

Figure 2: Griping the tab at the end of access panel, pull towards the rear and remove from unit.

Figure 3: Pull 3 pcs bezel hooks and remove the front bezel from chassis.

Figure 4: Unplug the cooler cable from PCA.

Figure 5: Release 4 screws from cooler and remove it (screw driver T15).

Figure 6: Disconnect the SATA and power cables from HDD.

PSG instructions for this template are available at EL-MF877-01
Figure 7 Release the HDD screws (screw driver T15)

Figure 8 Remove the HDD form chassis

Figure 9 Push the latch and release the Slim ODD.

Figure 10 Remove the Slim ODD form chassis.

Figure 11 Unplug all cable conn. from PCA.

Figure 12 Release 6 pcs screws from PCA (screw driver T15)

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 13  Remove PCA from chassis

Figure 14  Push the hooks on both sides and then pick up the memory

Figure 15  Rotate the handle and open it up

Figure 16  Remove the CPU from board

Figure 17  Remove the battery from the PCA

Figure 18  Release the screw of the FIO cable (screw driver T15)
Figure 19 Push the plastic hook and rotation the FIO module inside. Remove the FIO module from chassis.

Figure 20 Release the SD card reader screw (screw driver T15).

Figure 21 Remove the SD Card reader from chassis.

Figure 22 Release two screws of speaker.

Figure 23 Remove the speaker from chassis.

Figure 24 Release 2 pcs screws from system fan. (screw driver PH2)

PSG instructions for this template are available at EL-MF877-01
Figure 25  Remove the system fan from chassis

Figure 26  Release 4 pcs screws of PSU and remove it
(screw driver T15)

Figure 27  Pull up the PSU and remove it

Figure 28  Remove screw for top cover
(screw driver PH2)

Figure 29  Remove case cover

PSG instructions for this template are available at EL-MF877-01
Figure 30 Remove FG screw (screw driver PH2)

Figure 31 Disconnect fan connector

Figure 32 Disconnect the L/N wire connector

Figure 33 Cut the cable tie (Micro shear YN-3)

Figure 34 Remove PCB screw

Figure 35 Remove plastic cover

Figure 36 Remove AC inlet

Figure 37 Remove the FAN (screw driver PH2)
<table>
<thead>
<tr>
<th>Figure 38 Cut output cable (micro shear YN-3)</th>
<th>Figure 39 Remove capacitors use solder iron</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1" alt="Cable Image" /></td>
<td><img src="image2" alt="Solder Iron Image" /></td>
</tr>
<tr>
<td>Figure 40 Remove of Electrolytic Capacitors greater than 2.5cm in diameter or height (C801)</td>
<td></td>
</tr>
<tr>
<td><img src="image3" alt="Capacitor Image" /></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)